Approved for use through 04/30/2003. MB 0651-0032
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE
o a collection of information unless it displays a valid OMB control number. Paperwork Reduction Act of 1995, no persons are required to re

FE	Ε	TR	AN	SN	IIT	TAL
	1	or	FY	20	03	

Effective 01/01/2003. Patent fees are subject to annual revision.

Stephen B. Ackerman

Name (Print/Type)

Signature

Applicant claims small entity status. See 37 CFR 1.27

•		
TOTAL AMOUNT OF PAYMENT	(\$)	111

ODDITION OF STREET	STHIRD ATTICS IT CISDIAYS & VAIID CONTO CONTO HUMBE						
Complete if Known							
Application Number	10/054,001						
Filing Date	1/19/02						
First Named Inventor	Lin, M.S.						
Examiner Name	A. Chambliss						
Art Unit	2827						
Attorney Docket No.	MEG01-013						

METHOD OF PAYMENT (check all that apply)	FEE CALCULATION (continued)							
Check Credit card Money Other None	3. ADDITIONAL FEES							
Deposit Account:	Large Entity	Large Entity Small Entity						
Deposit	Fee Fee Code (\$)	ree Description						
Account Number 19-0033	Code (\$) 1051 130	ree i	Paid					
Deposit	1052 50		\dashv					
Account Name George O. Saile		cover sheet ——	\dashv					
The Commissioner is authorized to: (check all that apply)	1053 130	,	-					
Charge fee(s) indicated below Credit any overpayments	1812 2,520	, , , , , , , , , , , , , , , , , , , ,	\dashv					
Charge any additional fee(s) during the pendency of this application	1804 920	0* 1804 920* Requesting publication of SIR prior to Examiner action						
Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.	1805 1,840	0* 1805 1,840* Requesting publication of SIR after Examiner action						
FEE CALCULATION	1251 110	2251 55 Extension for reply within first month						
1. BASIC FILING FEE	1252 410	2252 205 Extension for reply within second month						
Large Entity Small Entity	1253 930	2253 465 Extension for reply within third month						
Fee Fee Fee Fee Description Fee Paid Code (\$)	1254 1,450	2254 725 Extension for reply within fourth month						
1001 750 2001 375 Utility filing fee	1255 1,970	2255 985 Extension for reply within fifth month	\longrightarrow					
1002 330 2002 165 Design filing fee	1401 320	2401 160 Notice of Appeal						
1003 520 2003 260 Plant filing fee	1402 320	2402 160 Filing a brief in support of an appeal						
1004 750 2004 375 Reissue filing fee	1403 280	2403 140 Request for oral hearing						
1005 160 2005 80 Provisional filing fee	1451 1,510	1451 1,510 Petition to institute a public use proceeding						
SUBTOTAL (1) (\$)	1452 110	2452 55 Petition to revive - unavoidable						
2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE	1453 1,300	2453 650 Petition to revive - unintentional						
Fee from _	1501 1,300							
Total Claims Extra Claims below Fee Paid	1502 470	2502 235 Design issue fee						
Independent 200	1503 630	2503 315 Plant issue fee						
Claims - 3 = L X L 3 = Multiple Dependent	1460 130	1460 130 Petitions to the Commissioner						
Lorgo Sutitus Consult Sur	1807 50	1807 50 Processing fee under 37 CFR 1.17(q)						
Large Entity Small Entity Fee Fee Fee Fee Fee Fee Fee Description	1806 180							
Code (\$) Code (\$)	8021 40	8021 40 Recording each patent assignment per property (times number of properties)						
1202 18 2202 9 Claims in excess of 20	1809 750		\dashv					
1201 84 2201 42 Independent claims in excess of 3		(37 ČFR 1.129(a))						
1203 280 2203 140 Multiple dependent claim, if not paid 1204 84 2204 42 ** Reissue independent claims	1810 750	2810 375 For each additional invention to be examined (37 CFR 1.129(b))						
over original patent	1801 750	2801 375 Request for Continued Examination (RCE)						
1205 18 2205 9 ** Reissue claims in excess of 20 and over original patent	1802 900	0 1802 900 Request for expedited examination of a design application						
SUBTOTAL (2) (\$)	Other fee (s	pecify)						
**or number previously paid, if greater; For Reissues, see above	*Reduced b	y Basic Filing Fee Paid SUBTOTAL (3) (\$) //O						
SUBMITTED BY (Complete (if applicable)								

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

Registration No.

37,761

Telephone 845-452-5863

June 4, 2003

Date

This collection of information is required by 37 CFR 1.17 and 1.27. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Washington, DC 20231.



May 28, 2003

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572

28 Davis Ave

Poughkeepsie, N.Y. 12603

Subject:

| Serial No. 10/054,001 01/19/02|

Mou-Shiung Lin

"THIN FILM SEMICONDUCTOR PACKAGE AND

METHOD OF FABRICATION"

| Grp. Art Unit: 2827 A. CHAMBLISS|

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated February 4, 2003, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on <u>June 4</u>

Stephen B. Ackerman, Reg. No. 37,761

Signature

06/09/2003 NMOHAMM1 00000032 190033 10054001

110.00 CH 01 FC:1251

1

MEG-01-013

In the Specification:

Please Amend the Title as follows:

THIN FILM SEMICONDUCTOR PACKAGE UTILIZING A GLASS SUBSTRATE WITH COMPOSITE POLYMER/METAL INTERCONNECT LAYERS

Please Amend the Specification, page 4, under DESCRIPTION OF DRAWINGS as follows:

Figs. 4a-41 show a fourth embodiment of the invention and the major fabrication steps.

Figs. 5a-51 show a fifth embodiment of the invention and the major fabrication steps.

Please Amend the Specification, page 7, paragraphs two and three as follows:

Multiple alternating layers of dielectric and metal (not shown) may be deposited and patterned until the final